

ABSTRACT

The present application provides a pressure monitoring apparatus, a semiconductor cleaning equipment, and a monitoring method thereof. The pressure monitoring apparatus comprises: a mounting frame, used to fixedly connect the pressure monitoring apparatus to a device under test; a swing rod, rotatably connected to the mounting frame, a force-receiving element being located on a first side of the swing rod; and a pressure sensor, located on a second side of the swing rod, the first side and the second side being arranged opposite to each other. When the swing rod is stressed, the swing rod swings between the force-receiving element and the pressure sensor; and the swing rod is provided with a first pressure contact portion and a second pressure contact portion. The first pressure contact portion is protrudingly arranged toward the first side, and the second pressure contact portion is protrudingly arranged toward the second side and is in contact with the pressure sensor. Wherein, when the force-receiving element receives pressure, the pressure is transmitted to the first pressure contact portion and makes the swing rod swing, so that the second pressure contact portion transmits the pressure to the pressure sensor.